TRU

Docket No.: 4425-324

PATEN'T

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	•	:			
Wei-Chi LIU et al.	•	:			
U.S. Patent Application No. 10/697,099			: Group Art Unit: 2814		
Filed: October 31, 2003			: Examiner: NATHAN HA		
For: THERMAL DIS	SSIPATING ELEN	MENT OF A CHIP			
Dear Sir:					
Transmitted herewith is	an Amendment ii	n the above identified	application.		
No additional fee i Small entity status Also attached: The fee has been calcula	of this application	n has been established	i.		
The fee has been calcula	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	20	20 ,	0	x \$ 18 =	\$ 0.00
Independent Claims	2	3	0	x \$ 88 =	\$ 0.00
		If multiple claims newly presented, add \$290.00 Fee for extension of time			
		ree for extension or t	mic	· · ·	
				TOTAL FEE DUE	\$ 0.00
The Commissioner	r is hereby author credit any overp	he amount of rized to charge payme ayment, to Deposit A n of extra claims and	ent of any <i>deficie</i> Account No. <u>07-1</u>	ncy in fees associate 337, including any	filing fees
		Dognootfully and	hmitted /		

Respectfully submitted,

LOWE ALUPTMAN GILMAN & BERNER, LLP

Benjamin J. Haupuman Registration No.: 29,310

USPTO Customer No. 22429 1700 Diagonal Road, Suite 300 Alexandria, Virginia 22314 (703) 684-1111 BJH/jk (703) 518-5499 Facsimile Date: December 9, 2004



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.

10/697,099

Applicant

Wei-Chi Liu et al

Filed

October 31, 2003

Title

Thermal Dissipating Element of a Chip

TC/A.U.

2814

Examiner

HA, NATHAN W

Docket No.

4425-324

Honorable Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

AMENDMENT

Sir:

This paper is in response to the Official Action mailed September 10, 2004. Applicants respectfully request that the Examiner reconsider the amended application according to the following remarks.

Please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begin on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.